

## REMARKS

Claims 1-8 and 14-16 are currently under examination. Claims 1, 2, 14 and 16 have been amended, and Claims 9-13 were previously withdrawn. Of the claims under examination, Claims 1 and 14 are independent. No new matter has been added. Reconsideration and further examination are respectfully requested.

A new Abstract including 50 to 150 words has been required. The Abstract has been amended in view of this requirement. Withdrawal of the objection to the Abstract is respectfully requested.

Claims 1-8 are rejected under 35 USC § 102(b) as being anticipated by U.S. Patent No. 6,435,883 B1 ("Warren"); and Claims 14-16 are rejected under 35 USC § 103(a) as being unpatentable over Warren in view of U.S. Publication No. 2005/0082650 A1 ("Kooi"). Withdrawal of the outstanding rejections is requested in light of the foregoing amendments and following remarks.

Amended independent Claim 1 relates to an apparatus including a pre-formed portion of underfill material defining openings. The openings are to pass electrical interconnects formed on a portion of a substrate, and the electrical interconnects are to couple an integrated circuit die to the portion of the substrate.

As an example of some embodiments, FIG. 1 of the present application illustrates portion 10 defining openings 15. As described at page 6, lines 4 through 6, "FIG. 9 shows electrical interconnects 70, which may be formed on substrate 50 before or after 86. Electrical interconnects 70 pass through respective ones of openings 15 and are used to couple IC substrate 50 to an IC die."

The art of record is not seen to disclose or suggest the above features of amended independent claim 1. In particular, the art of record is not seen to disclose or suggest a pre-formed portion of underfill material defining openings to pass electrical interconnects formed on a portion of a substrate.

Warren describes interconnect structure 10 to couple multichip interconnect decal 11 to printed wiring board 16. As described in column, 3, lines 21-43 of Warren, interconnect

structure 10 includes rigid transfer tape 14 defining an array of holes. Conductive epoxy is dispensed into the holes and is then partially cured to form conductive epoxy pads 15 within the holes. Interconnect structure 10, *including conductive pads 15*, is then placed on board 16. Next, decal 11 is placed on structure 10 such that pads 15 connect electrical elements of board 16 with electrical elements of decal 11.

Interconnect structure 10 of Warren therefore does not pass electrical interconnects that are formed on a portion of a substrate. Rather, conductive pads 15 are formed within structure 10 before structure 10 is placed on board 16. Accordingly, Warren cannot be seen to disclose or to suggest a pre-formed portion of underfill material defining openings to pass electrical interconnects formed on a portion of a substrate.

The remaining art of record has been reviewed and is not seen to remedy the foregoing deficiencies of Warren. Therefore, the art of record, taken in any permissible combination, is not seen to disclose or suggest a pre-formed portion of underfill material defining openings to pass electrical interconnects formed on a portion of a substrate.

In view of the foregoing, amended independent Claim 1 is believed to be in condition for allowance. Claims 2-8 depend from Claim 1 and are also believed to be in condition for allowance.

Amended independent Claim 14 concerns a system including a pre-formed portion of underfill material pre-formed to define openings, the openings passing a plurality of electrical interconnects formed on a substrate. Amended independent Claim 14 and dependent Claims 15 and 16 are therefore also believed to be allowable for at least the foregoing reasons.

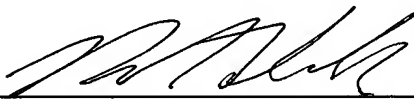
## CONCLUSION

The outstanding Office Action presents a number of characterizations regarding the applied references, some of which are not directly addressed herein because they are not related to the rejections of the independent claims. Applicant does not necessarily agree with the characterizations and reserve the right to further discuss those characterizations.

For at least the reasons given above, it is submitted that the entire application is in condition for allowance and such action is respectfully requested at the Examiner's earliest convenience. Alternatively, if there remains any question regarding the present application or any of the cited references, or if the Examiner has any further suggestions for expediting allowance of the present application, the Examiner is kindly invited to contact the undersigned via telephone at (203) 972-0049.

Respectfully submitted,

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Date

  
Nandu A. Talwalkar  
Registration No. 41,339  
Buckley, Maschoff & Talwalkar LLC  
Attorneys for Intel Corporation  
Five Elm Street  
New Canaan, CT 06840  
(203) 972-0049